

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT7867922

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jinsub LIM	10/12/2022
RECEIVING PARTY DATA	
Name:	LG ELECTRONICS INC.
Street Address:	128, YEOUNI-DAERO, YEONGDEUNGPO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	07336
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17974161
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	20172-0489001
NAME OF SUBMITTER:	AMANDA PETERSEN
SIGNATURE:	/Amanda Petersen/
DATE SIGNED:	03/27/2023
Total Attachments: 2	
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source=assignment#page2.tif	

ASSIGNMENT

For valuable consideration, the receipt of which I acknowledge, and intending to be bound legally, I, Jinsub LIM, assigns to LG ELECTRONICS INC., a corporation formed under the laws of Republic of Korea, and having a principal place of business at 128, Yeoui-daero, Yeongdeungpo-gu, Seoul 07336, Republic of Korea, and its successors, transferees, and assignees (collectively the "Assignee"), all of my individual and joint right, title, and interest throughout the world in the invention(s) (the "Subject Matter") described in a patent application that names me as inventor, is titled "MOTOR ASSEMBLY," and was or will be filed in the United States Patent and Trademark Office on October 26, 2022, as application 17/974,161 (the "Application"). I authorize the insertion of the filing date and application number above.

This Assignment assigns, in addition to the Subject Matter of the Application, (a) the Application and all other applications that may be made for, and all patents, utility models, design registrations, and other rights of exclusion and inventors' certificates for, any of the Subject Matter (collectively the "Applications and Granted Rights") in every country or region and under every treaty or convention, (b) the right to claim priority based on and the benefit of the filing date of any of the Applications and Granted Rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other applicable treaties or conventions, and (c) the right to pursue, collect, and retain in the Assignee's name or otherwise, damages and any other remedies arising from any past, present, or future infringement of the Subject Matter, the Applications and Granted Rights, and any other rights assigned by this Assignment.

I authorize the Assignee to apply for and pursue protection for any or all of the Subject Matter, the Applications and Granted Rights, and any other rights assigned by this Assignment in all countries, regions, and territories of the world, in my name or in the Assignee's name.

I represent and warrant that I have the right and power to make this Assignment and that I have not made and will not make any other assignment that conflicts with this Assignment.

I will communicate to the Assignee (or, at the request of the Assignee to other parties) all known facts in any form relating to the Subject Matter; will execute and provide all oaths and declarations, statements, testimony, assignments, powers of attorney, applications, and

documents; and will perform all other lawful acts necessary or desirable to secure fully to the Assignee the rights, titles, and interests assigned by this Assignment.



 Jinsub LIM

Date: 2022-10-12

Witnessed by:

Signature: _____

Date: _____

Print Name: _____

Signature: _____

Date: _____

Print Name: _____



The Assignee hereby acknowledges and accepts the foregoing assignment.

Assignee: LG ELECTRONICS INC.

Signature: _____

Date: _____

Name: _____

Title: _____